

# IR to UV ellipsometric characterization of silicon nitride thin films on textured Si wafers

UNIVERSITY OF NEBRASKA-LINCOLN

M. F. Saenger<sup>1,\*</sup>, M. Schädel<sup>3</sup>, T. Hofmann<sup>1</sup>, J. Hilfiker<sup>2</sup>, J. Sun<sup>2</sup>, T. E. Tiwald<sup>2</sup>, M. Schubert<sup>1</sup>, and J. A. Woollam<sup>1,2</sup>

<sup>1</sup> Department of Electrical Engineering, and Nebraska Center for Materials and Nanoscience, University of Nebraska-Lincoln, U.S.A.

<sup>2</sup> J. A. Woollam Co. Inc., Lincoln, Nebraska, U.S.A.

<sup>3</sup> Q-Cells A.G., Bitterfeld-Wolfen, Germany

\*saenger@engr.unl.edu  
http://ellipsometry.unl.edu

## Our message

The **film thickness** and optical constants can be determined for all the presented textures as well as a virtual void fraction.

**New method** for measuring thickness in structured c-Si substrates.

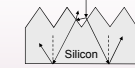
The **effective dielectric function** of Si<sub>3</sub>N<sub>4</sub> decreases depending on the texture. This can be described by an effective medium approximation consisting of a fully dense Si<sub>3</sub>N<sub>4</sub> film and void optical constants.

**IR data** of the chemical bond mode amplitude and resonance energy distribution suggests a change in the chemical composition of the films in dependence on the texture.

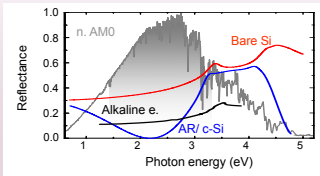
## Introduction

Minimize optical losses in solar cells  
Trapping of light techniques:

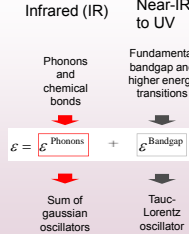
- ✓ Surface texturization [1]
- ✓ Anti-reflecting films



$$d_{AR} = \lambda / 4n(\lambda)$$



Silicon nitride  
Model Dielectric Function

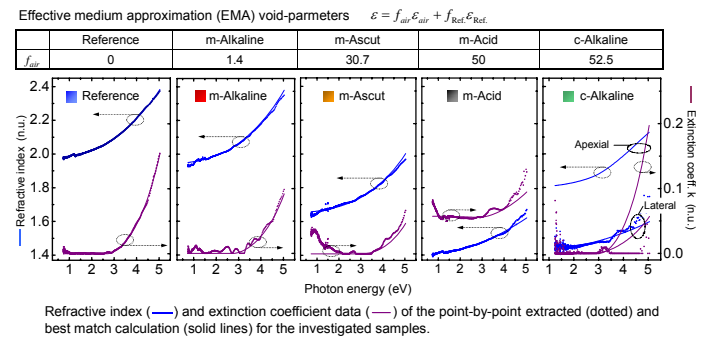
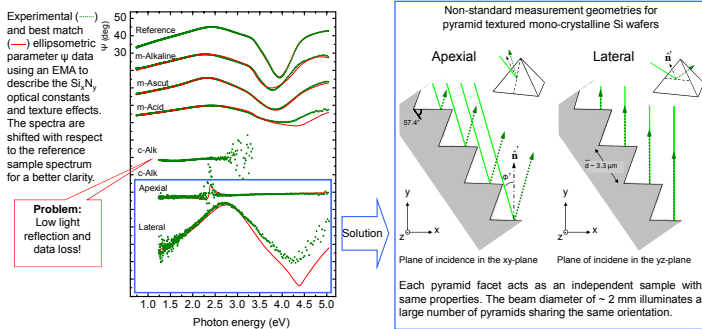


Samples: PECVD grown Si<sub>3</sub>N<sub>4</sub> films on textured Si

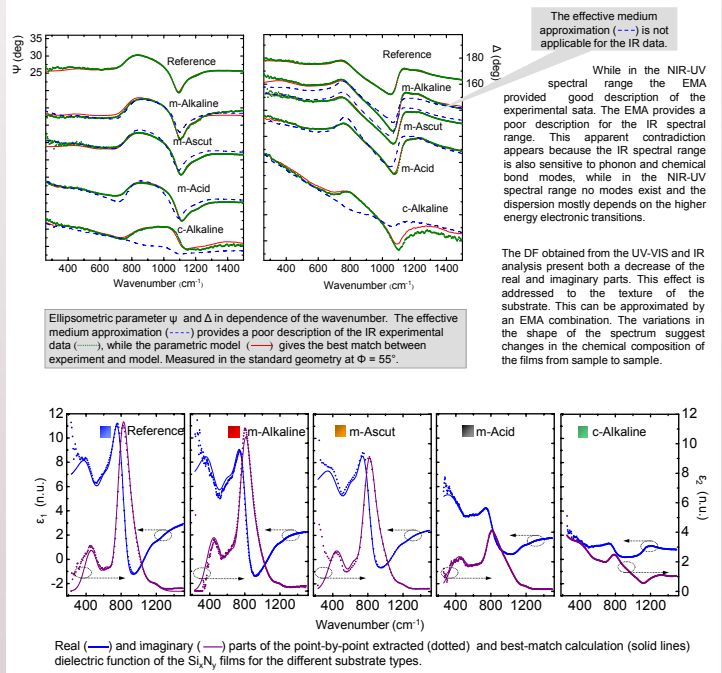
Name	Wafer type	Wafer treatment	Substrate morphology
Reference	crystalline-Si	Polished (no texture)	15 cm
c-Alk	crystalline-Si	Alkaline etched	20 μm
m-Alk	Multi-crystalline Si	Alkaline etched	50 μm
m-Acid		Acid etched	50 μm
m-Ascult		As-cut	20 μm

## Results and Discussions

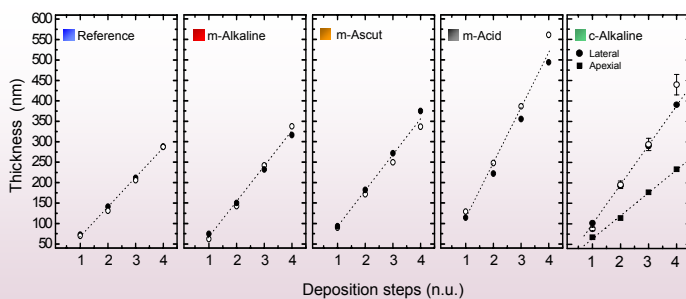
### UV-VIS: New measurement method and texture effects



### IR: Chemical bond modes and texture effects



### Thickness results



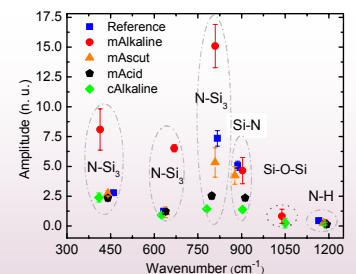
Thickness parameter values plotted versus deposition steps for the different textured wafers obtained from the UV-VIS (●, ■) and IR (○) ellipsometry data analysis.

### Chemical modes

#### Gaussian oscillator model

$$\epsilon_2'' = A e^{-\frac{(E-E_0)^2}{B}} + A e^{-\frac{(E+E_0)^2}{B}}$$

Changes in the chemical bond modes amplitude and resonance energy parameter values suggest changes in the film chemistry from substrate to substrate. Mode assignment after references [2-4].



Oscillator amplitude versus resonance energy model parameters for the investigated samples.

#### References

- [1] J. D. Hylton et al., J. Electrochem. Soc., 151, G408 (2004).
- [2] Z. Yin, et al., Phys. Rev. B 42, 3666 (1990).
- [3] M. Klarjšek Gunde et al., Phys. Status Solidi A 183 (2), 439 (2001).
- [4] J. J. Mei, et al., J. Appl. Phys. 100, 073516 (2006).